

NO. QTY.	DESCRIPTION OF PRODUCT	UNIT (in EUR)
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1	EVG6200NT Semi-automated Bottom Side Mask Alignment System without Lamphouse (up to 200 mm, double side, manual handling) For wafer size up to 200 mm	
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1	1 Basic Unit - Double Side Mask Alignment System <ul style="list-style-type: none"> • Exposure modes: hard-, soft- and vacuum contact, proximity • Separation distance 0 - 300 µm adjustable via software • Wafer thickness 0.1 - 10 mm (for top side configuration only) • Semi automatic loading with mechanical prealignment on chuck • Quick change of mask and chuck • One storage rack for up to five (5) aligner tools • EC Declaration of Conformity (certification done by EVG) • PC controlled operating environment • Solid state drive and hard drive for high availability and reliability • Graphical User Interface (GUI) for visualization • User interface including keyboard and monitor • Granite base frame construction and active vibration isolation 	
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1	1 NRTL Certification <ul style="list-style-type: none"> • NRTL listing mark • Conforms to UL61010-1: Electrical Equipment for Laboratory Use – General Requirements 	
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1	1 SEMI S2/S8 Certification <ul style="list-style-type: none"> • SEMI S2 listing mark • System certified according SEMI S2-0310 ENVIRONMENTAL, HEALTH, AND SAFETY GUIDELINE FOR SEMICONDUCTOR MANUFACTURING EQUIPMENT This guideline applies to equipment used to manufacture, measure, assemble, and test semiconductor products. • System certified according SEMI S8-0308 ERGONOMICS ENGINEERING OF SEMICONDUCTOR MANUFACTURING EQUIPMENT The guidelines address safety aspects of ergonomics engineering in the design of semiconductor manufacturing equipment. It should be noted that in order to ensure comprehensive coverage of potential safety hazards, some guidelines also address general design goals for effective human-machine performance. The guidelines apply to the design, operation, maintenance, and service of semiconductor manufacturing equipment, as well as, to a limited extent, equipment installation 	
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1	1 Facility connections through machine sidewall <ul style="list-style-type: none"> • Does not require a cleanroom with raised floor / sub floor 	
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1	1 Software <ul style="list-style-type: none"> • Microsoft Windows® based process software for recipes, processing and diagnostics • Automated recording of process parameters • Storage of files and presets on hard disk or network • Password protected access levels for operator, engineer and maintenance 	
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2	1 System Hardware Preparation for Bond Alignment <ul style="list-style-type: none"> • Mechanical preparation with bond tool clamping mechanism for standard bond tool size • Mandatory to enable bond alignment and recommended if bond alignment is considered as later field upgrade 	
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